DALLAS
SEMICONDUCTOR

4401 South Beltwood Parkway
Dallas, Texas 75244-3292
(972) 371-4000

Date: 06/02/00

Subject: **PRODUCT CHANGE NOTICE – F000102**

Description: DS1921 Die and Assembly Construction Revision Changes

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Description of Change:

The DS1921 die has been revised to eliminate the possibilities of a datalog memory mis-read condition within the device and of a race condition resulting in page-0 data corruption.

Additionally, the DS1921 iButton is being modified to allow use of Dallas Semiconductor's solder bump technology in place of the existing wire bond process. Both construction techniques may be used to increase manufacturing capacity.

Devices Affected:

DS1921L-F51, -F52, -F53

Traceability:

Devices will be branded with the following revision markings.

Brand	Die Revision	Construction	Begins shipping
A3	Current, A3	Wire Bond	Currently
A5	New, A5	Wire Bond	July 1, 2000
B5	New, A5	Solder Bump	3rd Quarter 2000

Qualification Status:

The new revision will be produced using the same fabrication process as the current revision. This process is qualified, and the new revision will reach qualification based on characterization of the changed circuit function and reliability testing evaluation of one lot.

The solder bump assembly process has been granted full qualification status by the Reliability Department at Dallas Semiconductor.

For further information, please contact any of the people listed below.

Mr. Jacques Marineau	Product Engineering Manager	(972) 371-6661 / FAX (972) 371-4178
Mr. Richard Shine	QA Engineering Manager	(972) 371-3874 / FAX (972) 371-6016

Sincerely,

Philip A. Adams
Director Quality and Reliability Assurance